

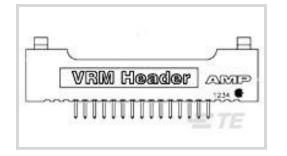
AMPMODU | AMPMODU Headers

TE Internal #: 146205-1 PCB Mount Header, Vertical, Board-to-Board, 30 Position, .1 in [2.54 mm] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **30**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded

Printed Circuit Board

Configuration Features

PCB Mount Orientation	Vertical
Number of Positions	30
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Dielectric Withstanding Voltage (Max)	750 VACrms
Operating Voltage	250 VAC
Body Features	
Primary Product Color	Black
Contact Features	
Contact Layout	Inline
Mating Square Post Dimension	.64 mm[.025 in]
	100 – 250 µin

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PCB Contact Termination Area Plating Material Finish	Bright	
Contact Shape & Form	Square	
PCB Contact Termination Area Plating Material	Tin-Lead	
Contact Base Material	Copper Alloy	
Contact Mating Area Plating Material	Gold	
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]	
Contact Type	Pin	
Contact Current Rating (Max)	2 A	
Termination Features		
Square Termination Post & Tail Dimension	.64 mm[.025 in]	
Termination Post & Tail Length	3.05 mm[.12 in]	
Termination Method to Printed Circuit Board	Through Hole - Solder	
Mechanical Attachment		
Mating Retention	Without	
Mating Alignment	With	
Mating Alignment Type	Card Edge Slot	
PCB Mount Retention	Without	
PCB Mount Alignment	Without	
Connector Mounting Type	Board Mount	
Housing Features		
Centerline (Pitch)	2.54 mm[.1 in]	
Housing Material	Thermoplastic	
Dimensions		
Connector Height	13.97 mm[.55 in]	
Row-to-Row Spacing	2.54 mm[.1 in]	
Stack Height	10.41 mm[.41 in]	
PCB Thickness (Recommended)	1.57 mm[.062 in]	
	1.57 mm[.062 in]	
Usage Conditions	1.57 mm[.062 in]	
Usage Conditions Operating Temperature Range	1.57 mm[.062 in] -65 – 105 °C[-85 – 221 °F]	
Operating Temperature Range		

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Industry Standards

Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	32
Packaging Type	Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.

Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

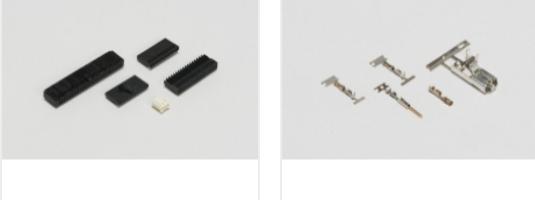
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Also in the Series | AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(66)
& Housings(5)	

Customers Also Bought

e TE	E TE	K-KATTIN- K-W-W-	
TE Part #2204929-3 MATING BLADE, CROWN CLIP SOCKET	TE Part #2307725-8 8P,2MM,B-B,REC,SRHZ,SMD,0.1AU,TR	TE Part #3-6450830-3 MBXL R/A HDR 4ACP + 12S + 3P	TE Part #6-6450830-1 MBXL R/A HDR 3HDP+1LP+24S+1LP+3HDP
CIERCINAL ALAR			
TE Part #1-6450121-1 MBXL R/A HDR 24S+4P	TE Part #2-6450831-1 MBXLE R/A HDR 24S	TE Part #2159452-1 C/A, TERMINAL + 14 AWG WIRE+ HALF STRIPP	TE Part #2159453-1 C/A, TERMINAL + 14 AWG WIRE+ HALF STRIPP

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TE Part #2321493-4 BUS BAR ASSEMBLY, CROWN CLIP SOCKET

Documents

Product Drawings 30 MODII 2PC VRM7 HDR W/LATCH

English

Product Specifications

Application Specification

English

AMPMODU Mod II 2-Piece Double Row Header Assemblies

English